



PMBT3906MB

40 V, 200 mA PNP switching transistor

Rev. 1 — 2 April 2012

Product data sheet

1. Product profile

1.1 General description

PNP single switching transistor in a leadless ultra small DFN1006B-3 (SOT883B) Surface-Mounted Device (SMD) plastic package.

NPN complement: PMBT3904MB.

1.2 Features and benefits

- Single general-purpose switching transistor
- AEC-Q101 qualified
- Ultra small SMD plastic package
- Board-space reduction
- Low package height of 0.37 mm

1.3 Applications

- General-purpose switching and amplification
- Mobile applications

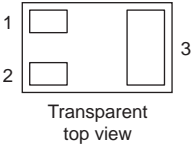
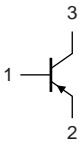
1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CE0}	collector-emitter voltage	open base	-	-	-40	V
I_C	collector current		-	-	-200	mA
h_{FE}	DC current gain	$V_{CE} = -1$ V; $I_C = -10$ mA	100	180	300	

2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	base		
2	emitter		
3	collector		

sym013



3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMBT3906MB	DFN1006B-3	leadless ultra small plastic package; 3 solder lands; body 1.0 × 0.6 × 0.37 mm	SOT883B

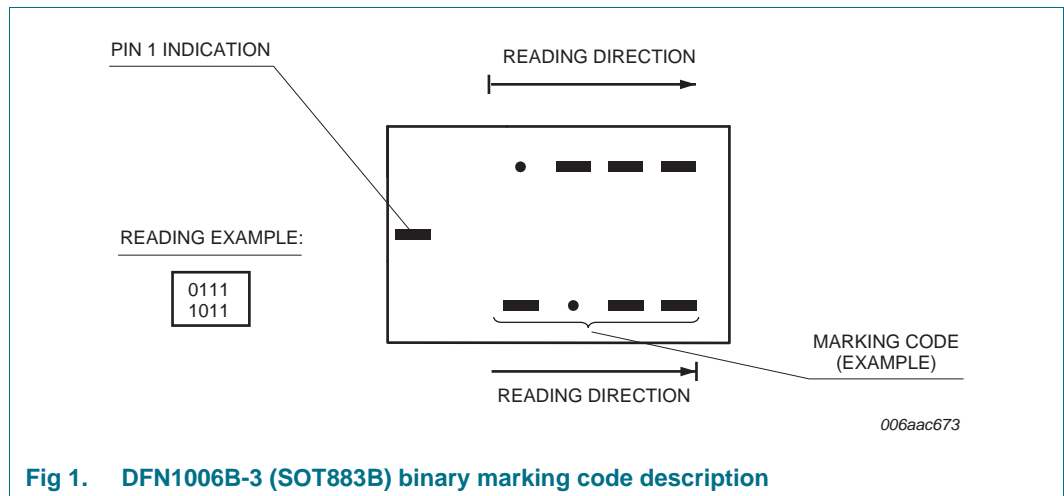
4. Marking

Table 4. Marking codes

Type number	Marking code ^[1]
PMBT3906MB	0100 1000

[1] For DFN1006B-3 (SOT883B) binary marking code description, see [Figure 1](#).

4.1 Binary marking code description



5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit	
V_{CBO}	collector-base voltage	open emitter	-	-40	V	
V_{CEO}	collector-emitter voltage	open base	-	-40	V	
V_{EBO}	emitter-base voltage	open collector	-	-6	V	
I_C	collector current		-	-200	mA	
I_{CM}	peak collector current	single pulse; $t_p \leq 1$ ms	-	-200	mA	
I_{BM}	peak base current	single pulse; $t_p \leq 1$ ms	-	-100	mA	
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C	[1][2]	-	250	mW
			[1][3]	-	590	mW
T_j	junction temperature		-	150	°C	
T_{amb}	ambient temperature		-55	+150	°C	
T_{stg}	storage temperature		-65	+150	°C	

[1] Reflow soldering is the only recommended soldering method.

[2] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 1 cm².

6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1][2]	-	-	500	K/W
			[1][3]	-	-	212	K/W

- [1] Reflow soldering is the only recommended soldering method.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 1 cm².

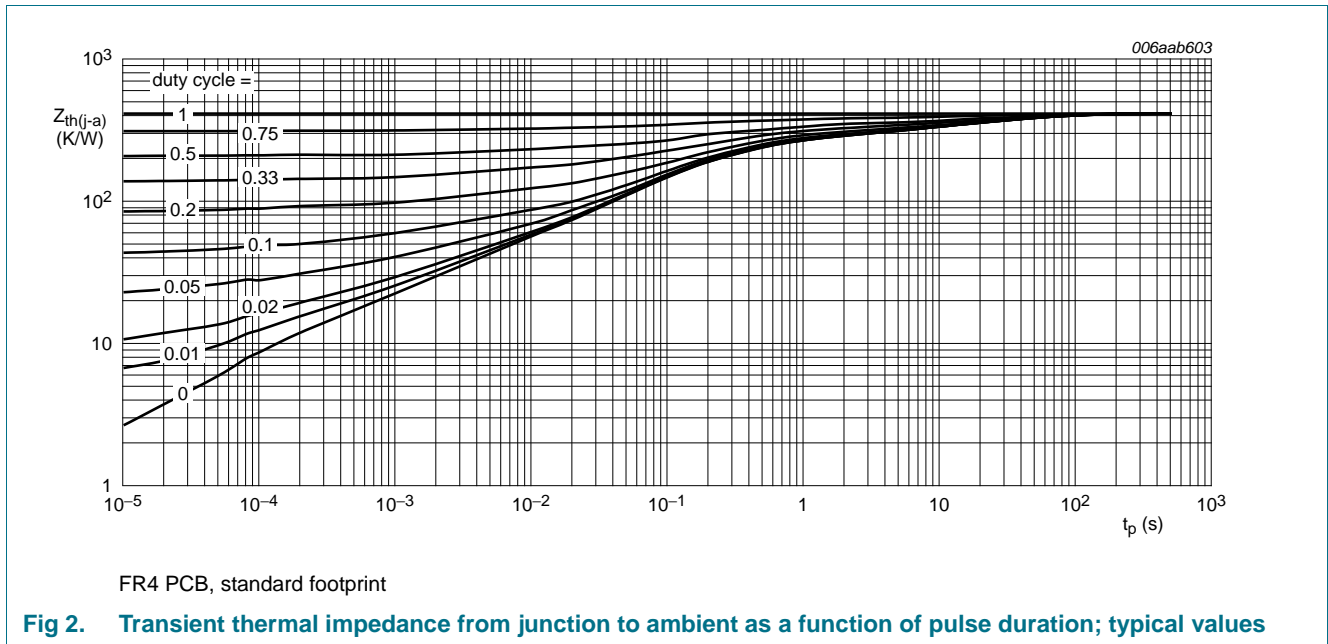


Fig 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

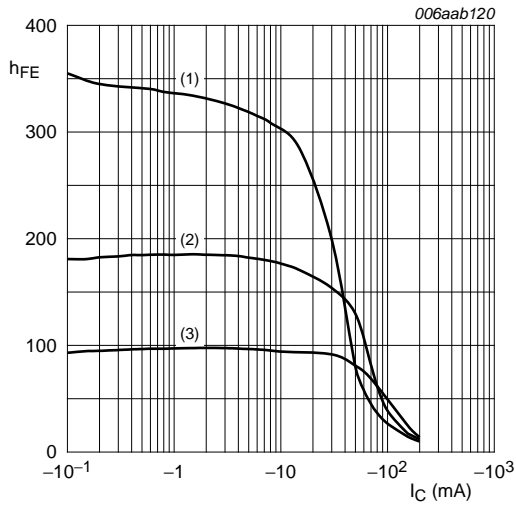
7. Characteristics

Table 7. Characteristics

$T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

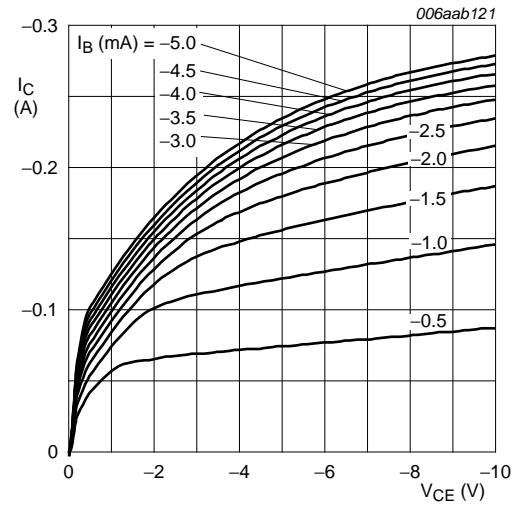
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_{CBO}	collector-base cut-off current	$V_{CB} = -30\text{ V}; I_E = 0\text{ A}$	-	-	-50	nA
I_{EBO}	emitter-base cut-off current	$V_{EB} = -6\text{ V}; I_C = 0\text{ A}$	-	-	-50	nA
h_{FE}	DC current gain	$V_{CE} = -1\text{ V}$				
		$I_C = -0.1\text{ mA}$	60	180	-	
		$I_C = -1\text{ mA}$	80	180	-	
		$I_C = -10\text{ mA}$	100	180	300	
		$I_C = -50\text{ mA}$	60	130	-	
V_{CEsat}	collector-emitter saturation voltage	$I_C = -10\text{ mA}; I_B = -1\text{ mA}$	-	-100	-250	mV
		$I_C = -50\text{ mA}; I_B = -5\text{ mA}$	-	-165	-400	mV
V_{BEsat}	base-emitter saturation voltage	$I_C = -10\text{ mA}; I_B = -1\text{ mA}$	-	-750	-850	mV
		$I_C = -50\text{ mA}; I_B = -5\text{ mA}$	-	-850	-950	mV
t_d	delay time	$V_{CC} = -3\text{ V};$ $I_C = -10\text{ mA};$	-	-	35	ns
t_r	rise time	$I_{Bon} = -1\text{ mA};$	-	-	35	ns
t_{on}	turn-on time	$I_{Boff} = 1\text{ mA}$	-	-	70	ns
t_s	storage time		-	-	225	ns
t_f	fall time		-	-	75	ns
t_{off}	turn-off time		-	-	300	ns
C_c	collector capacitance	$V_{CB} = -5\text{ V}; I_E = I_e = 0\text{ A};$ $f = 1\text{ MHz}$	-	-	4.5	pF
C_e	emitter capacitance	$V_{EB} = -500\text{ mV};$ $I_C = I_c = 0\text{ A}; f = 1\text{ MHz}$	-	-	10	pF
f_T	transition frequency	$V_{CE} = -20\text{ V};$ $I_C = -10\text{ mA};$ $f = 100\text{ MHz}$	250	-	-	MHz
NF	noise figure	$V_{CE} = -5\text{ V};$ $I_C = -100\text{ }\mu\text{A}; R_S = 1\text{ k}\Omega;$ $f = 10\text{ Hz to }15.7\text{ kHz}$	-	-	4	dB

[1] Pulse test: $t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02$.



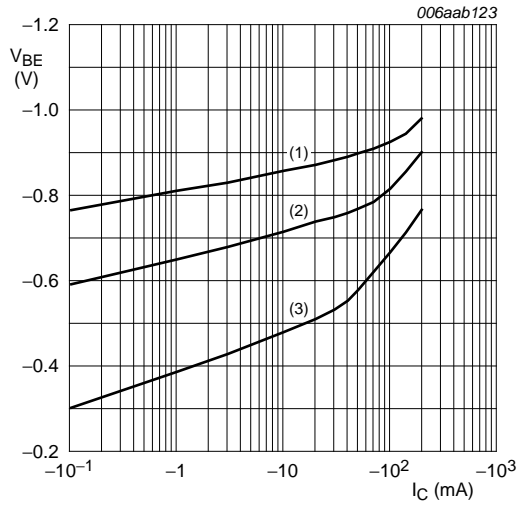
- $V_{CE} = -1\text{ V}$
- (1) $T_{amb} = 150\text{ }^{\circ}\text{C}$
 - (2) $T_{amb} = 25\text{ }^{\circ}\text{C}$
 - (3) $T_{amb} = -55\text{ }^{\circ}\text{C}$

Fig 3. DC current gain as a function of collector current; typical values



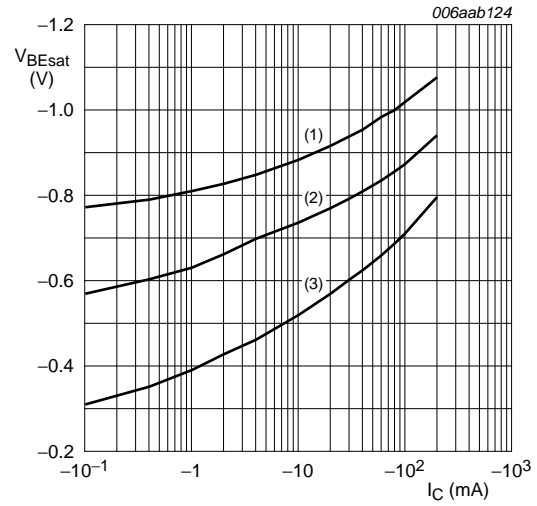
$T_{amb} = 25\text{ }^{\circ}\text{C}$

Fig 4. Collector current as a function of collector-emitter voltage; typical values



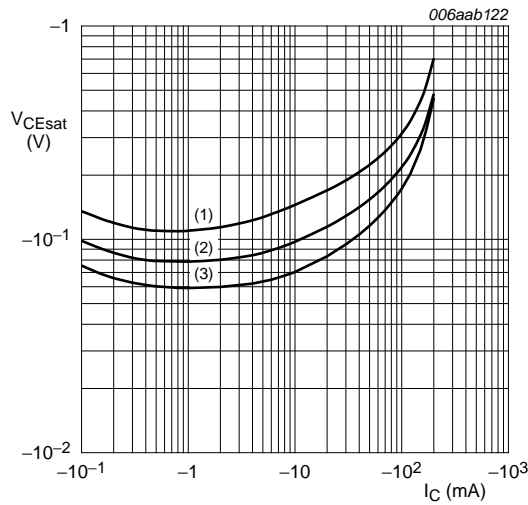
$V_{CE} = -1\text{ V}$
 (1) $T_{amb} = -55\text{ °C}$
 (2) $T_{amb} = 25\text{ °C}$
 (3) $T_{amb} = 150\text{ °C}$

Fig 5. Base-emitter voltage as a function of collector current; typical values



$I_C/I_B = 10$
 (1) $T_{amb} = -55\text{ °C}$
 (2) $T_{amb} = 25\text{ °C}$
 (3) $T_{amb} = 150\text{ °C}$

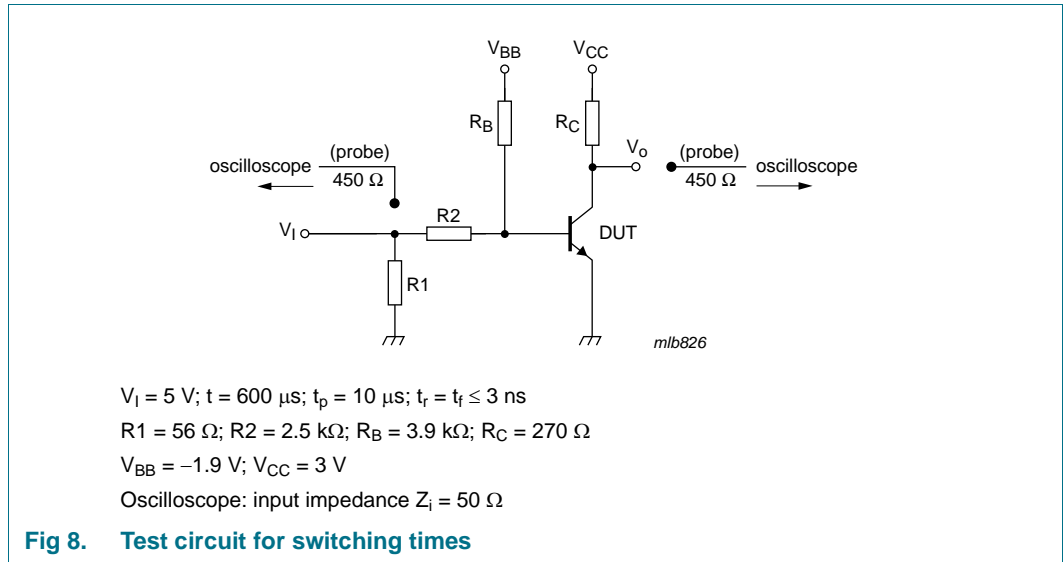
Fig 6. Base-emitter saturation voltage as a function of collector current; typical values



$I_C/I_B = 10$
 (1) $T_{amb} = 150\text{ °C}$
 (2) $T_{amb} = 25\text{ °C}$
 (3) $T_{amb} = -55\text{ °C}$

Fig 7. Collector-emitter saturation voltage as a function of collector current; typical values

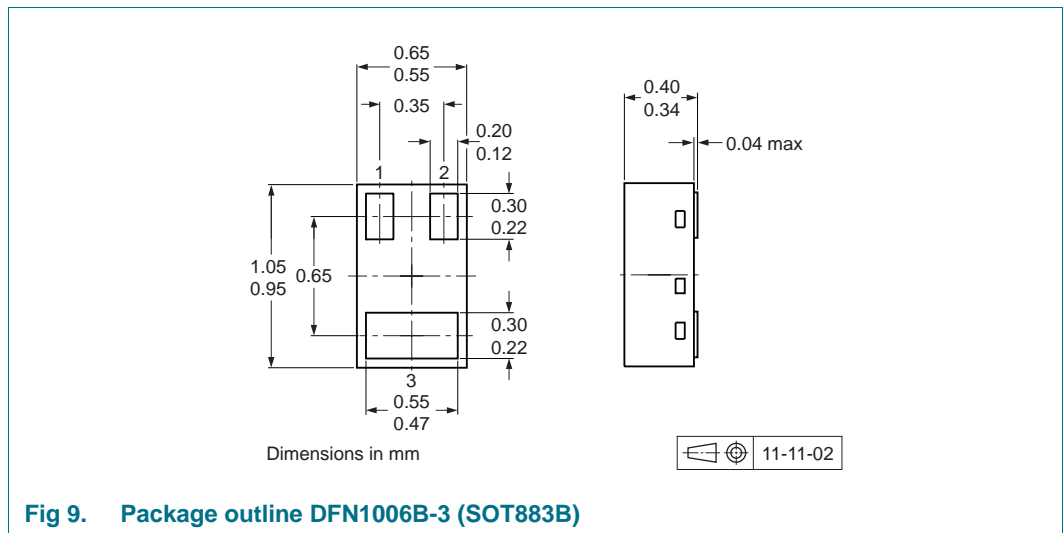
8. Test information



9. Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - *Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

10. Package outline



11. Packing information

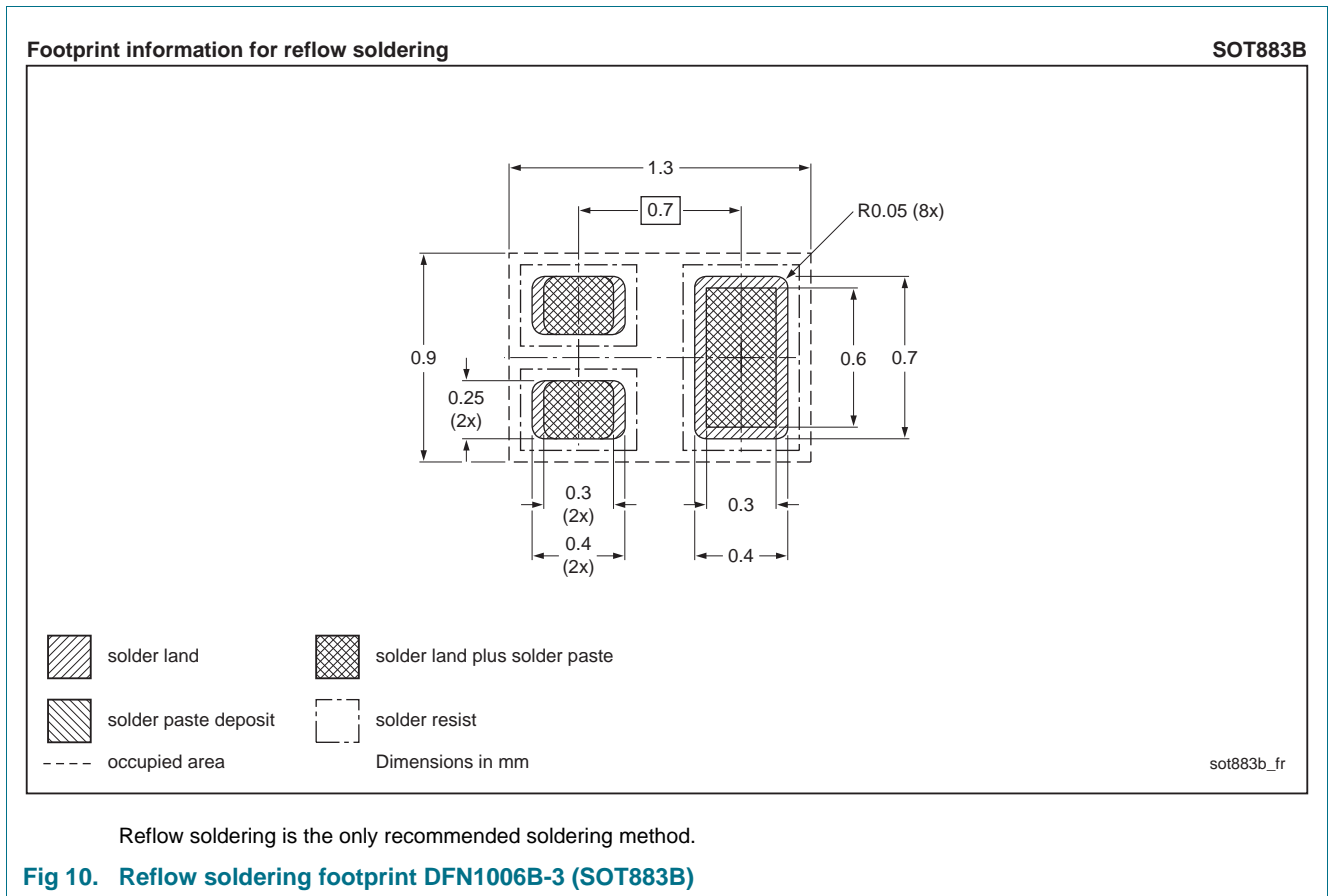
Table 8. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.^[1]

Type number	Package	Description	Packing quantity
			10000
PMBT3906MB	DFN1006B-3 (SOT883B)	2 mm pitch, 8 mm tape and reel	-315

[1] For further information and the availability of packing methods, see [Section 15](#).

12. Soldering



13. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PMBT3906MB v.1	20120402	Product data sheet	-	-

14. Legal information

14.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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